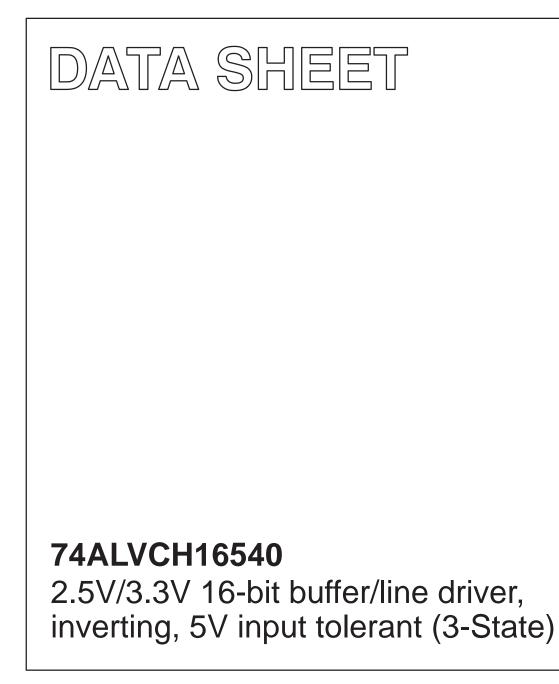
INTEGRATED CIRCUITS



Product specification Supersedes data of 1996 Feb 07 IC24 Data Handbook

1997 Aug 11





74ALVCH16540

29 2A5

28 GND

27 2A6 26 2A7

25 20E2

SW00108

FEATURES

- Wide supply voltage range of 1.2 V to 3.6 V
- Complies with JEDEC standard no. 8-1A
- CMOS low power consumption
- MULTIBYTETM flow-through standard pin-out architecture
- Low inductance multiple V_{CC} and ground pins for minimum noise and ground bounce
- Direct interface with TTL levels
- Bus hold on all data inputs eliminates the need for external pull-up resistors to hold unused inputs
- Output drive capability 50Ω transmission lines @ 85°C

DESCRIPTION

The 74ALVCH16540 is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

The 74ALVCH16540 is a 16-bit inverting buffer/line driver with 3-State outputs. The 3-State outputs are controlled by the output enable inputs $1\overline{OE}_n$ and $2\overline{OE}_n$. A HIGH on $n\overline{OE}_n$ causes the outputs to assume a high impedance OFF-state.

Active bus hold circuitry is provided to hold unused or floating data inputs at a valid logic level. This feature eliminates the need for external pull-up or pull-down resistors. The device can be used as four 4-bit buffers, two 8-bit buffers or one 16-bit buffer.

10E ₁ 1	48	8 1 0E 2
1 <u>Y0</u> 2	47	7 1A0
1 <u>71</u> 3	40	6 1A1
GND 4	45	5 GND
1 <u>72</u> 5	44	4 1A2
1 7 3 6	43	3 1A3
V _{CC} 7	42	2 V _{CC}
1 <u>74</u> 8	41	1 1A4
1 <u>75</u> 9	40	0 1A5
GND 10	39	9 GND
176 11	38	8 1A6
1 \ 77 12	37	7 1A7
2 <u>Y0</u> 13	36	6 2A0
2 <u>Y1</u> 14	35	5 2A1
GND 15	34	4 GND
2 <u>Y2</u> [16	33	3 2A2
2 \] 3	32	2 2A3
V _{CC} [18	3	1 V _{CC}
2 \4 19	30	0 2A4

2<u>75</u>20

GND 21

2<u>76</u> 22

 $2\overline{Y7}$ 23 20E1 24

PIN CONFIGURATION

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONI	TYPICAL	UNIT	
+/+	Propagation delay 1An to 1Yn;	C _L = 50pF V _{CC} = 3.3V		1.8	ns
t _{PHL} /t _{PLH}	2An to 2Yn	$C_L = 30 pF$ $V_{CC} = 2.5 V$		1.8	ns
CI	Input capacitance			5.0	pF
C	Power dissipation capacitance per buffer	$V_{\rm c} = CND$ to $V_{\rm c} = 1$	Outputs enabled	26	pF
C _{PD}	D Power dissipation capacitance per buffer	VI = GIAD to ACC.	$V_{I} = GND \text{ to } V_{CC}^{1}$ Outputs disabled		

NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μ W):

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma \ (C_L \times V_{CC}^2 \times f_o) \ \text{where:}$ $f_i = \text{input frequency in MHz; } C_L = \text{output load capacitance in pF;}$

 f_o = output frequency in MHz; V_{CC} = supply voltage in V;

 Σ (C_L × V_{CC}² × f₀) = sum of outputs.

ORDERING INFORMATION

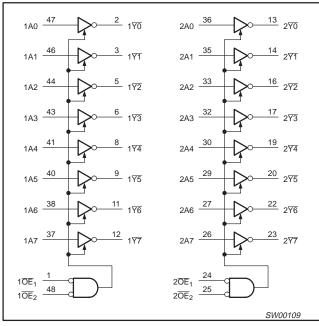
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
48-Pin Plastic SSOP Type III	–40°C to +85°C	74ALVCH16540 DL	ACH16540 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ALVCH16540 DGG	ACH16540 DGG	SOT362-1

74ALVCH16540

PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 24	n <mark>OE</mark> 1	Output enable input (active LOW)
2, 3, 5, 6, 8, 9, 11, 12	1Y0 to 1Y7	
13, 14, 16, 17, 19, 20, 22, 23	2Y0 to 2Y7	Data outputs
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground (0V)
7, 18, 31, 42	V _{CC}	Positive supply voltage
25, 48	$n\overline{OE}_2$	Output enable input (active LOW)
36, 35, 33, 32, 30, 29, 27, 26	2A0 to 2A7	
47, 46, 44, 43, 41, 40, 38, 37	1A0 to 1A7	Data inputs

LOGIC SYMBOL



FUNCTION TABLE

	INPUTS		OUTPUT
nOE ₁	$n\overline{OE}_2$	nAn	nYn
L	L	L	Н
L	L	Н	L
Х	Н	Х	Z
Н	Х	Х	Z

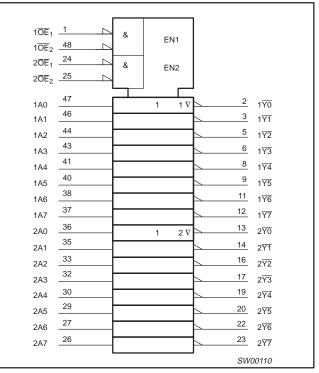
H = HIGH voltage level

L = LOW voltage level

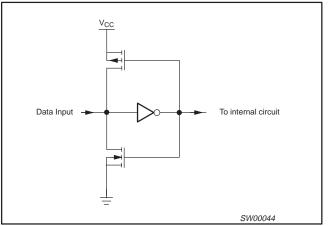
X = don't care

Z = high impedance OFF-state

LOGIC SYMBOL (IEEE/IEC)



BUS HOLD CIRCUIT



74ALVCH16540

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIN	IITS	UNIT
STWBUL	PARAMETER	CONDITIONS	MIN	MAX	
	DC supply voltage 2.5V range (for max. speed performance)		2.3	2.7	
V _{CC}	DC supply voltage 3.3V range (for max. speed performance)		3.0	3.6	V
	DC supply voltage (for low-voltage applications)		1.2	3.6	1
V	DC Input voltage range	For data input pins	0	V _{CC}	v
VI	DC Input voltage range	For control pins	0	5.5	v
Vo	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 2.3 \text{ to } 3.0 \text{V}$ $V_{CC} = 3.0 \text{ to } 3.6 \text{V}$	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V ₁ < 0	-50	mA
VI	DC input voltage	For control pins and data inputs of ALVC parts ²	-0.5 to +5.5	V
		For data inputs of ALVCH parts ²	–0.5 to V _{CC} +0.5	1
I _{OK}	DC output diode current	$V_{O} > V_{CC} \text{ or } V_{O} < 0$	±50	mA
Vo	DC output voltage	Note 2	–0.5 to V _{CC} +0.5	V
Ι _Ο	DC output source or sink current	$V_{O} = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package -plastic medium-shrink SO (SSOP) -plastic mini-pack (TSSOP)	For temperature range: -40 to +125 °C above +55°C derate linearly with 11.3 mW/K above +55°C derate linearly with 8 mW/K	850 600	mW

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

74ALVCH16540

DC ELECTRICAL CHARACTERISTICS

				L	IMITS		
SYMBOL	PARAMETER	TEST CONDITIO	NS	Temp = -			
		MIN	TYP ¹	MAX			
		$V_{CC} = 1.2V$		V _{CC}			
V_{IH}	HIGH level Input voltage	V _{CC} = 2.3 to 2.7V	/ _{CC} = 2.3 to 2.7V				V
		V _{CC} = 2.7 to 3.6V		2.0]
		$V_{CC} = 1.2V$				GND	
V _{IL}	LOW level Input voltage	V _{CC} = 2.3 to 2.7V				0.7	V [
		V _{CC} = 2.7 to 3.6V				0.8]
		V_{CC} = 2.3V; V_{I} = V_{IH} or V_{IL} ; I_{O} =	-1mA	$V_{CC}-0.3$			Γ
		V_{CC} = 2.3V; V_{I} = V_{IH} or V_{IL} ; I_{O} =	8mA	V _{CC} -0.5			1
V _{OH}	HIGH level output voltage	V_{CC} = 2.7V; V_{I} = V_{IH} or V_{IL} ; I_{O} =	V _{CC} -0.5			l v	
		$V_{CC} = 2.3/3.0V$; $V_I = V_{IH}$ or V_{IL} ;	I _O = −100μA	V _{CC} -0.2	V _{CC}		1
		V_{CC} = 3.0V; V_I = V_{IH} or V_{IL} ; I_O =	V _{CC} -1.0			1	
		V_{CC} = 2.3V; V_{I} = V_{IH} or V_{IL} ; I_{O} =	1mA			0.40	
		V_{CC} = 2.3V; V_{I} = V_{IH} or V_{IL} ; I_{O} = 8mA				0.60	1
V _{OL}	LOW level output voltage	V_{CC} = 2.7V; V_{I} = V_{IH} or V_{IL} ; I_{O} =	: 12mA			0.40	1 v
		$V_{CC} = 2.3/3.0V; V_I = V_{IH} \text{ or } V_{IL};$	I _O = 100μA			0.20	1
	V_{CC} = 3.0V; V_{I} = V_{IH} or $V_{IL;}$ I _O = 24mA					0.55	1
		V_{CC} = 3.6V; V_{I} = 5.5V or GND	Control pins		±0.1	±5	
ł	Input leakage current	V_{CC} = 3.6V; V_{I} = V_{CC} or GND	Data input pins		±0.1	±5	μ/
I _{IHZ} /I _{ILZ}	Input current for common I/O pins	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or } GND$			±0.1	±15	μA
1	3-State output OFF-state current	V_{CC} = 3.6V; V_{I} = V_{IH} or V_{IL} ; V_{O}	= V _{CC} or GND		0.1	±10	
I _{OZ}	3-State output OFF-state current	V_{CC} = 2.7V; V_{I} = V_{IH} or V_{IL} ; V_{O}	= V _{CC} or GND		0.1	±5	μ/
1	Quiescent supply current	V_{CC} = 3.6V; V_{I} = V_{CC} or GND; I	_O = 0		0.2	40	
ICC	Quiescent supply current	V_{CC} = 2.7V; V_{I} = V_{CC} or GND; I	_O = 0		0.2	20	μA
Al	Additional quiescent supply current per control pin	$V_{CC} = 2.7V$ to 3.6V; $V_{I} = V_{CC} - 0$	0.6V; I _O = 0		5	500	μΑ
ΔI _{CC}	Additional quiescent supply current per data I/O pin	$V_{CC} = 2.7V$ to 3.6V; $V_{I} = V_{CC} - 0.000$	V_{CC} = 2.7V to 3.6V; V_{I} = V_{CC} –0.6V; I_{O} = 0			750	μ <i>μ</i> -
IBHL	Bus hold LOW sustaining current	$V_{CC} = 2.3V; V_I = 0.7V$		45			μA
IDHE		$V_{CC} = 3.0V; V_I = 0.8V$		75			μ
IBHH	Bus hold HIGH sustaining current	V _{CC} = 2.3V; V _I = 1.7V		-45			μ/
		$V_{CC} = 3.0V; V_{I} = 2.0V$		-75			
IBHLO	Bus hold LOW overdrive current	V _{CC} = 2.7V		300			/
		V _{CC} = 3.6V		450			μ/
ІВННО	Bus hold HIGH overdrive current	V _{CC} = 2.7V		-300			/
		V _{CC} = 3.6V		-450			μA

NOTES:

1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

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AC CHARACTERISTICS FOR V_{CC} = 3.0V TO 3.6V RANGE AND V_{CC} = 2.7V

GND = 0V; $t_r = t_f \le 2.5ns$; $C_L = 50pF$

					LIM	ITS		
SYMBOL	PARAMETER	WAVEFORM	٧ _c	$_{\rm C}$ = 3.0 ± 0.	3V	V _{CC} =	: 2.7V	UNIT
			MIN	TYP ¹	MAX	ТҮР	MAX	1
t _{PHL} /t _{PLH}	Propagation delay 1An to 1Yn; 2An to 2Yn	4		1.8	3.0	2.1	3.6	ns
t _{PZH} /t _{PZL}	3-State output enable time 1OEn to 1Yn; 2OEn to 2Yn	5, 6		2.1	3.8	2.9	4.7	ns
t _{PHZ} /t _{PLZ}	3-State output disable time 10En to 1Yn; 20En to 2Yn	5, 6		2.7	4.1	3.2	4.5	ns

NOTE:

1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25° C.

AC CHARACTERISTICS FOR V_{CC} = 2.3V TO 2.7V RANGE AND V_{CC} < 2.3V

GND = 0V; $t_r = t_f \le 2.0$ ns; $C_L = 30$ pF

			LIM			ITS		
SYMBOL	PARAMETER	WAVEFORM	Vcc	; = 2.3 to 2	2.7V	V _{CC} = 1.8V	V _{CC} = 1.2V	UNIT
			MIN	TYP ¹	MAX	TYP	MAX	
t _{PHL} /t _{PLH}	Propagation delay 1An to 1Yn; 2An to 2Yn	4		1.8	3.2	3.1	6.0	ns
t _{PZH} /t _{PZL}	3-State output enable time 10En to 1Yn; 20En to 2Yn	5, 6		2.5	4.4	4.3	8.9	ns
t _{PHZ} /t _{PLZ}	3-State output disable time 10En to 1Yn; 20En to 2Yn	5, 6		2.2	3.8	3.6	6.4	ns

NOTE:

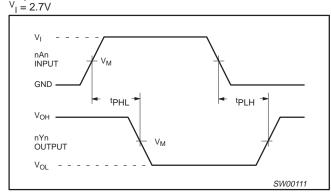
1. All typical values are at V_{CC} = 2.5V and T_{amb} = 25°C.

AC WAVEFORMS FOR V_{CC} = 3.0V TO 3.6V AND V_{CC} = 2.7V RANGE

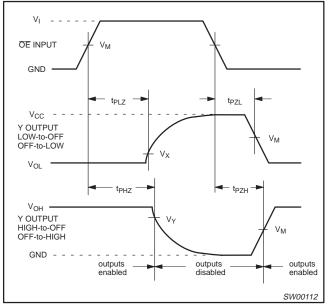
V_M = 1.5 V

 $V_{X} = V_{OL} + 0.3V$

 V_{Y} = V_{OH} –0.3V V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.



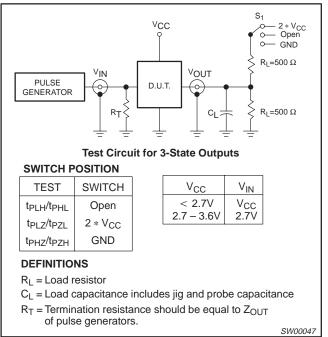




Waveform 2. 3-State enable and disable times

74ALVCH16540

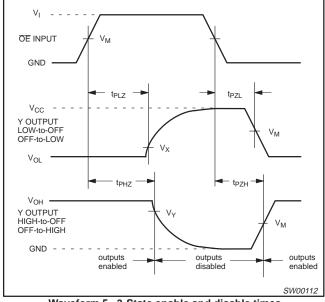
TEST CIRCUIT



Waveform 3. Load circuitry for switching times

AC WAVEFORMS FOR V_{CC} = 2.3V TO 2.7V AND V_{CC} < 2.3V RANGE

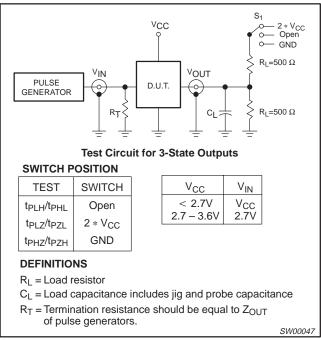




Waveform 5. 3-State enable and disable times

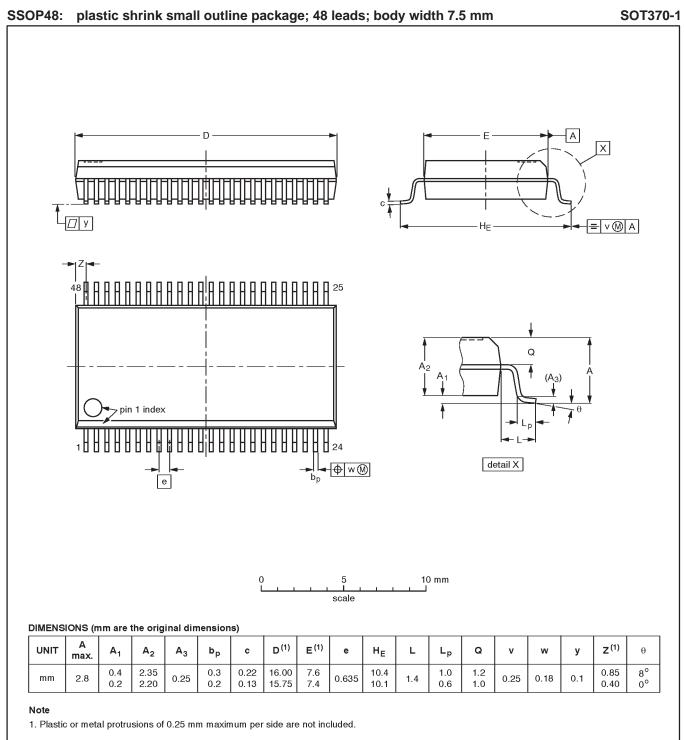
74ALVCH16540

TEST CIRCUIT



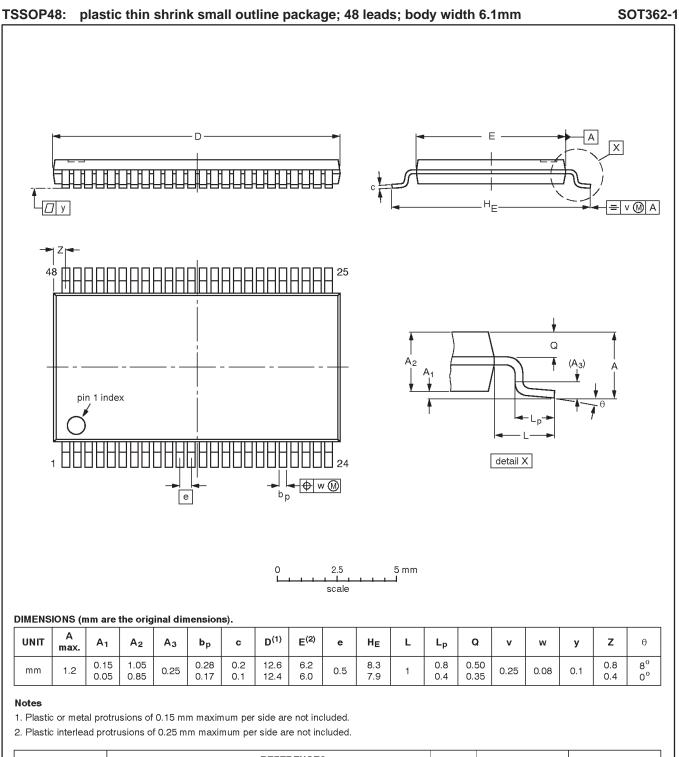
Waveform 6. Load circuitry for switching times

74ALVCH16540



OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT370-1		MO-118AA			-93-11-02 95-02-04

74ALVCH16540



VERSION IEC JEDEC EIAJ PROJECTION	OUTLINE		REFER	ENCES		EUROPEAN	ISSUE DATE
	VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE
SOT362-1 MO-153ED 95-02-10	SOT362-1		MO-153ED				

74ALVCH16540

NOTES

74ALVCH16540

DEFINITIONS		
Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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